ne<mark>x</mark>peria

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Should be replaced with:

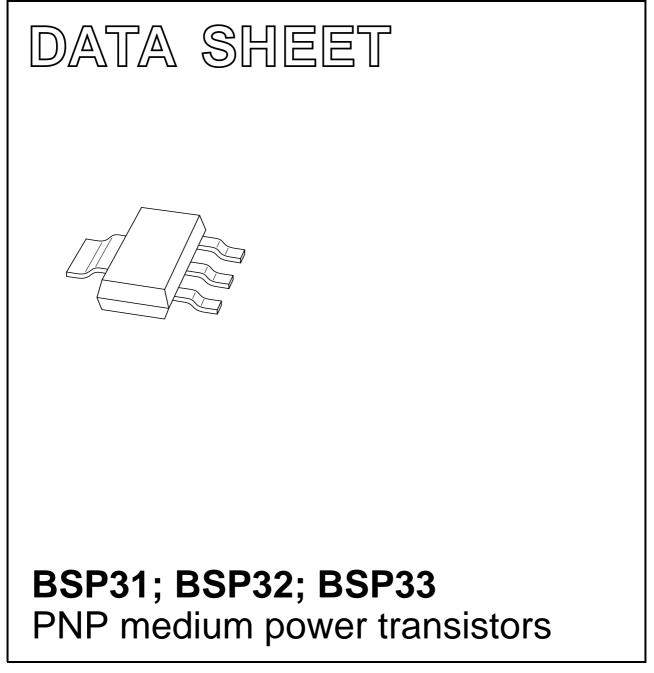
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1997 Apr 08 1999 Apr 26



FEATURES

- High current (max. 1 A)
- Low voltage (max. 80 V).

APPLICATIONS

• Telephony and general industrial applications.

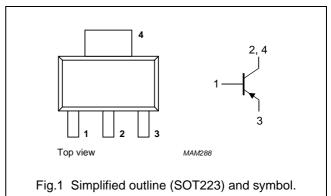
DESCRIPTION

PNP medium power transistor in a SOT223 plastic package. NPN complements: BSP41 and BSP43.

BSP31; BSP32; BSP33

PINNING

PIN	DESCRIPTION
1	base
2, 4	collector
3	emitter



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CBO}	collector-base voltage	open emitter			
	BSP31		-	-70	V
	BSP32; BSP33		-	-90	V
V _{CEO}	collector-emitter voltage	open base			
	BSP31		_	-60	V
	BSP32; BSP33		-	-80	V
V _{EBO}	emitter-base voltage	open collector	_	-5	V
I _C	collector current (DC)		_	-1	А
I _{CM}	peak collector current		—	-2	А
I _{BM}	peak base current		—	-200	mA
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	_	1.3	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

BSP31; BSP32; BSP33

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	note 1	93	K/W	
R _{th j-s}	thermal resistance from junction to soldering point		12	K/W	

Note

1. Device mounted on a printed-circuit board, single sided copper, tinplated, mounting pad for collector 1 cm². For other mounting conditions, see *"Thermal considerations for SOT223 in the General Part of associated Handbook"*.

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

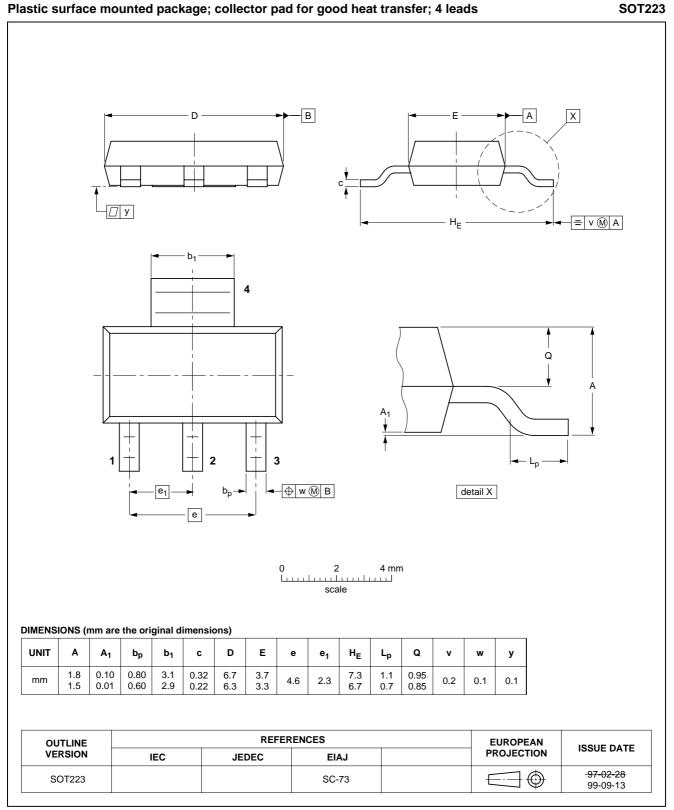
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = -60 V	—	-100	nA
		I _E = 0; V _{CB} = -60 V; T _j = 150 °C	_	-50	μA
I _{EBO}	emitter cut-off current	$I_{C} = 0; V_{EB} = -5 V$	_	-100	nA
h _{FE}	DC current gain				
1	BSP32	$I_{C} = -100 \ \mu A; V_{CE} = -5 \ V; \text{ note } 1$	10	_	
		I _C = -100 mA; V _{CE} = -5 V; note 1	40	120	
		I _C = -500 mA; V _{CE} = -5 V; note 1	30	-	
	DC current gain				
	BSP31; BSP33	$I_{C} = -100 \ \mu A; V_{CE} = -5 \ V; \text{ note } 1$	30	_	
		I _C = -100 mA; V _{CE} = -5 V; note 1	100	300	
		I _C = –500 mA; V _{CE} = –5 V; note 1	50	_	
V _{CEsat}	collector-emitter saturation voltage	$I_{C} = -150 \text{ mA}; I_{B} = -15 \text{ mA}; \text{ note } 1$	_	-250	mV
		$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	_	-500	mV
V _{BEsat}	base-emitter saturation voltage	IC = -150 mA; IB = -15 mA; note 1	_	-1	V
		$I_{C} = -500 \text{ mA}; I_{B} = -50 \text{ mA}; \text{ note } 1$	_	-1.2	V
C _c	collector capacitance	I _E = i _e = 0; V _{CB} = -10 V; f = 1 MHz	—	20	pF
Ce	emitter capacitance	$I_{C} = i_{c} = 0$; $V_{EB} = -0.5$ V; f = 1 MHz	_	120	pF
f _T	transition frequency	$I_{C} = -50 \text{ mA}; V_{CE} = -10 \text{ V}; \text{ f} = 100 \text{ MHz}$	100	_	MHz
Switching	times (between 10% and 90% leve	els)	•	•	•
t _{on}	turn-on time	$I_{Con} = -100 \text{ mA}; I_{Bon} = -5 \text{ mA}; I_{Boff} = 5 \text{ mA}$	-	500	ns
t _{off}	turn-off time		_	650	ns

Note

1. Pulse test: $t_p \le 300 \ \mu s$; $\delta \le 0.01$.

BSP31; BSP32; BSP33

PACKAGE OUTLINE



BSP31; BSP32; BSP33

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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NXP Semiconductors

Customer notification

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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